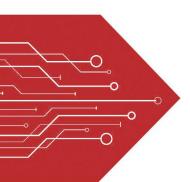
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet



SOT-223



1. BASE

- 2. COLLECTOR
- 3. EMITTER

PNP Transistors

■ Features

- Collector Current Capability Ic=-4A
- Collector Emitter Voltage VcEo=-140V
- Very low saturation voltages

Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit	
Collector - Base Voltage	Vсво	-180		
Collector - Emitter Voltage	VCEO	-140	V	
Emitter - Base Voltage	Vево	-6		
Collector Current - Continuous	lc	-4	А	
Peak Pulse Current	Ісм	-10		
Collector Power Dissipation	Pc	3	W	
Thermal Resistance, Junction to Ambient (Note 1)	Reja	78	°C/W	
Operating and Storage Temperature Range	TJ,Tstg	-55 to 150	$^{\circ}$	

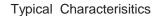
Note 1:For a device mounted with the collector lead on 25mm x 25mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still airconditions whilst operating in steady-state.

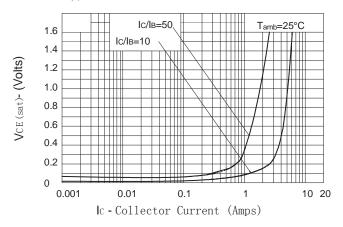
Electrical Characteristics Ta = 25°C

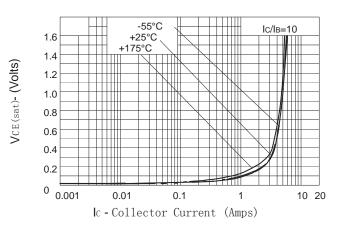
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Collector- base breakdown voltage	VCBO Ic= -100 μA, IE=0		-180				
Collector- emitter breakdown voltage	VCER	Ic=-1 μA, Rв ≤ 1kΩ	-180			V	
Collector- emitter breakdown voltage	VCEO	Ic= -10 mA, IB=0	-140				
Emitter - base breakdown voltage	VEBO	IE= -100 μA, IC=0	-6				
Collector-base cut-off current	Ісво	Vcb= -150 V , IE=0			-50	nA	
Collector-base cut-on current		Vcb= -150 V , IE=0 , Ta = 100° C			-1	μΑ	
Collector cut-off current R < 1kΩ	ICER	VCE= -150 V , IE=0			-50	nA	
Collector cut-on current 1/ < 1/22	ICER	Vce= -150 V , Ie=0 , Ta = 100° C			-1	μΑ	
Emitter cut-off current	ІЕВО	VEB= -6V , IC=0			-10	nA	
Collector-emitter saturation voltage		Ic=-100 mA, IB=-5 mA			-60	mV	
	VCE(sat)	Ic=-500 mA, Iв=-50mA			-120		
		Ic=-1 A, IB=-100mA			-150		
		Ic=-3 A, IB=-300mA			-370		
Base - emitter saturation voltage	VBE(sat)	Ic=-3 A, IB=-300mA			-1110		
Base - emitter turn-on voltage	VBE(on)	VCE= -5V, IC= -3A			-950		
DC current gain	hFE	VCE= -5V, IC= -10mA	100				
		VCE=- 5V, IC= -1 A	100		300		
		VCE= -5V, IC= -3 A	75				
		VCE= -5V, IC= -10 A		10			
Switching Times	ton	IC=-1A, IB1=-100mA		68		ns	
	toff	IB2=100mA, Vcc=-50V		1030			
Collector output capacitance	Cob	Vcb= -20V,f=1MHz		40		pF	
Transition frequency	f⊤	VcE= -10V, Ic= -100mA,f=50MHz		110		MHz	



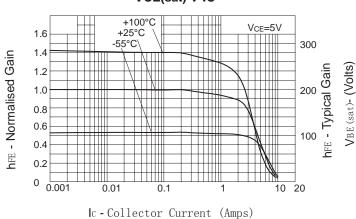




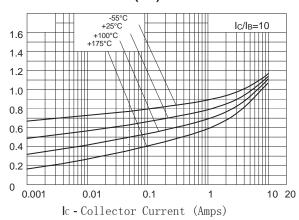




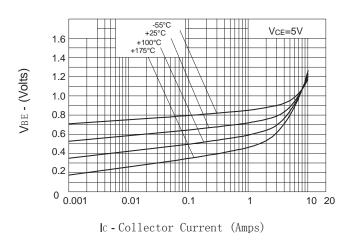
VCE(sat) v IC



VCE(sat) v IC

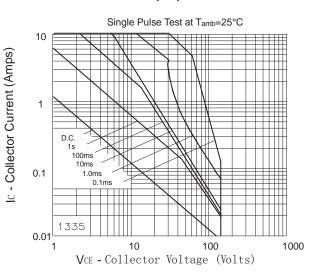


hFE v IC



VBE(on) v IC

VBE(sat) v IC



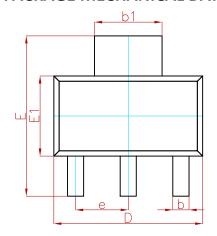
Safe Operating Area

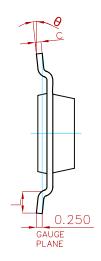


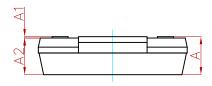
Semiconductor

Compiance

PACKAGE MECHANICAL DATA

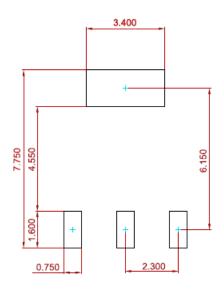






Symbol Dimensions In Millimeter		n Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α		1.800		0.071	
A1	0.020	0.100	0.001	0.004	
A2	1.500	1.700	0.059	0.067	
b	0.660	0.840	0.026	0.033	
b1	2.900	3.100	0.114	0.122	
С	0.230	0.350	0.009	0.014	
D	6.300	6.700	0.248	0.264	
E	6.700	7.300	0.264	0.287	
E1	3.300	3.700	0.130	0.146	
е	2.300(BSC)		0.091(BSC)		
L	0.750		0.030		
θ	0°	10°	0°	10°	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters. 2.General tolerance:±0.050mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
FZT955-MS	SOT-223	1000



Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specificationsof any andall MSKSEMI Semiconductor products described orcontained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- MSKSEMI Semiconductor. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with someprobability. It is possiblethat these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits anderror prevention circuitsfor safedesign, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from theauthorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringementsof intellectual property rights or other rightsof third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. Whendesigning equipment, referto the "Delivery Specification" for the MSKSEMI Semiconductor productthat you intend to use.